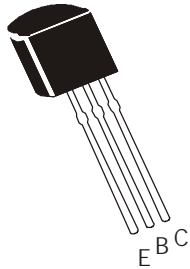


NPN/PNP SILICON PLANAR EPITAXIAL TRANSISTORS



**MPSA05, MPSA06
MPSA55, MPSA56**

**TO-92
Plastic Package**

Amplifier Transistors

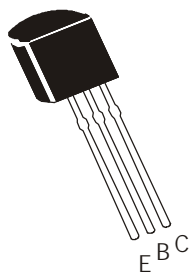
ABSOLUTE MAXIMUM RATINGS(Ta=25°C unless otherwise specified)

DESCRIPTION	SYMBOL	MPSA05 MPSA55	MPSA06 MPSA56	UNITS
Collector Emitter Voltage	V_{CEO}	60	80	V
Collector Base Voltage	V_{CBO}	60	80	V
Emitter Base Voltage	V_{EBO}		4	V
Collector Current Continuous	I_C		500	mA
Total Device Dissipation@Ta=25°C	P_D		625	mW
Derate Above 25°C			5.0	mW/°C
Total Device Dissipation@ Tc=25°C	P_D		1.5	W
Derate Above 25°C			12	mW/°C
Operating And Storage Junction Temperature Range	T_j, T_{stg}		-55 to +150	°C
THERMAL RESISTANCE				
Junction to ambient	$R_{th(j-a)} (1)$		200	°C/mW
Junction to case	$R_{th(j-c)}$		83.3	°C/mW

(1) $R_{th(j-a)}$ is measured with the device soldered into a typical printed circuit board.

NPN SILICON PLANAR EPITAXIAL TRANSISTORS

**MPSA05,MPSA06
MPSA55,MPSA56**



**TO-92
Plastic Package**

ELECTRICAL CHARACTERISTICS (Ta=25°C Unless Otherwise Specified)

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
Collector Emitter Voltage	V_{CE0} *	$I_C=1mA, I_B=0$				
			MPSA05/55	60		V
	MPSA06/56		80		V	
Emitter-Base Voltage	V_{EBO}	$I_E=100\mu A, I_C=0$	4.0			V
Collector-Cut off Current	I_{CBO}					
			MPSA05/55			0.1
	MPSA06/56				0.1	μA
Collector-Cut off Current	I_{CEO}	$V_{CE}=60V, I_B=0$			0.1	μA
Collector-Emitter (sat) Voltage	$V_{CE(sat)}$	$I_C=100mA, I_B=10mA$			0.25	V
Base-Emitter(on) Voltage	$V_{BE(on)}$	$I_C=100mA, V_{CE}=1V$			1.2	V
DC Current Gain	h_{FE}	$V_{CE}=1V, I_C=10mA$	100			
				$V_{CE}=1V, I_C=100mA$	100	

ELECTRICAL CHARACTERISTICS (Ta=25°C Unless Otherwise Specified)

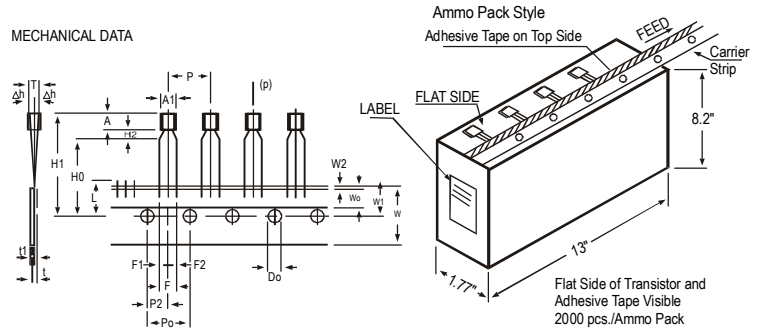
DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS	
DYNAMIC CHARACTERISTICS						
Transition Frequency	NPN	f_T^{**}	$I_C=10mA, V_{CE}=2V$	100		MHz
	PNP		$I_C=100mA, V_{CE}=1V$	50		MHz
			$f=100MHz$			

*Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

** f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.

TO-92 Plastic Package

TO-92 Transistors on Tape and Ammo Pack

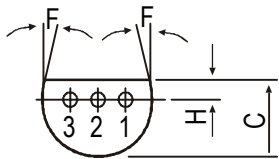
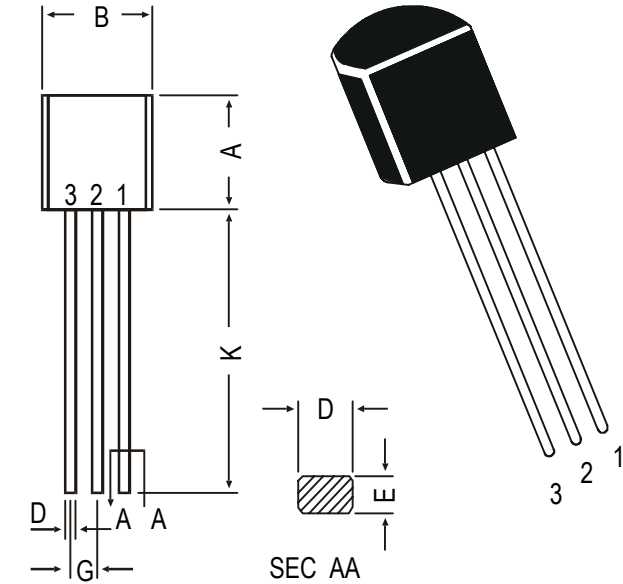


All dimensions in mm unless specified otherwise

ITEM	SYMBOL	SPECIFICATION				REMARKS
		MIN.	NOM.	MAX.	TOL.	
BODY WIDTH	A1	4.0		4.8		
BODY HEIGHT	A	4.8		5.2		
BODY THICKNESS	T	3.9		4.2		
PITCH OF COMPONENT	P		12.7		±1	
FEED HOLE PITCH	Po		12.7		±0.3	
FEED HOLE CENTRE TO COMPONENT CENTRE	P2		6.35		±0.4	CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH TO BE MEASURED AT BOTTOM OF CLINCH
DISTANCE BETWEEN OUTER LEADS	F		5.08		+0.6 -0.2	
COMPONENT ALIGNMENT	Δh		0	1		AT TOP OF BODY
TAPE WIDTH	W		18		±0.5	
HOLD-DOWN TAPE WIDTH	W0		6		±0.2	
HOLE POSITION	W1		9		+0.7 -0.5	
HOLD-DOWN TAPE POSITION	W2		0.5		±0.2	
LEAD WIRE CLINCH HEIGHT	Ho		16		±0.5	
COMPONENT HEIGHT	H1			23.25		
LENGTH OF SNIPPED LEADS	L			11.0		
FEED HOLE DIAMETER	Do		4		±0.2	
TOTAL TAPE THICKNESS	t			1.2		t1 0.3 - 0.6
LEAD - TO - LEAD DISTANCE F1,	F2		2.54		+0.4 -0.1	
CLINCH HEIGHT	H2			3		
PULL - OUT FORCE	(P)	6N				

NOTES

1. MAXIMUM ALIGNMENT DEVIATION BETWEEN LEADS NOT TO BE GREATER THAN 0.2 mm.
2. MAXIMUM NON-CUMULATIVE VARIATION BETWEEN TAPE FEED HOLES SHALL NOT EXCEED 1 mm IN 20 PITCHES.
3. HOLDDOWN TAPE NOT TO EXCEED BEYOND THE EDGE(S) OF CARRIER TAPE AND THERE SHALL BE NO EXPOSURE OF ADHESIVE.
4. NO MORE THAN 3 CONSECUTIVE MISSING COMPONENTS ARE PERMITTED.
5. A TAPE TRAILER, HAVING AT LEAST THREE FEED HOLES ARE REQUIRED AFTER THE LAST COMPONENT.
6. SPLICES SHALL NOT INTERFERE WITH THE SPROCKET FEED HOLES.



- PIN CONFIGURATION**
1. COLLECTOR
 2. BASE
 3. EMITTER

All dimensions in mm.

DIM	MIN.	MAX.
A	4.32	5.33
B	4.45	5.20
C	3.18	4.19
D	0.41	0.55
E	0.35	0.50
F	5 DEG	
G	1.14	1.40
H	1.14	1.53
K	12.70	—

Packing Detail

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5.0K	17" x 15" x 13.5"	80.0K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2.0K	17" x 15" x 13.5"	32.0K	12.5 kgs

Disclaimer

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Continental Device India Limited

C-120 Naraina Industrial Area, New Delhi 110 028, India.

Telephone + 91-11-2579 6150, 5141 1112 Fax + 91-11-2579 5290, 5141 1119

email@cdil.com www.cdilsemi.com